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Vishay Semiconductors

Ultrafast Rectifier, 8 A FRED Pt®



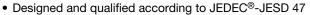
LINKS TO ADDITIONAL RESOURCES



PRIMARY CHARACTERISTICS									
I _{F(AV)}	8 A								
V _R	200 V								
V _F at I _F	0.895 V								
t _{rr} typ.	See Recovery table								
T _J max.	175 °C								
Package	TO-220AC 2L								
Circuit configuration	Single								

FEATURES

- Ultrafast recovery time
- Low forward voltage drop
- 175 °C operating junction temperature
- · Low leakage current



 Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

DESCRIPTION / APPLICATIONS

VS-MUR820 is the state of the art ultrafast recovery rectifier specifically designed with optimized performance of forward voltage drop and ultrafast recovery time.

The planar structure and the platinum doped life time control, guarantee the best overall performance, ruggedness and reliability characteristics.

These devices are intended for use in the output rectification stage of SMPS, UPS, DC/DC converters as well as freewheeling diode in low voltage inverters and chopper motor drives.

Their extremely optimized stored charge and low recovery current minimize the switching losses and reduce over dissipation in the switching element and snubbers.

MECHANICAL DATA

Case: TO-220AC

Molding compound meets UL 94 V-0 flammability rating **Terminals:** matte tin plated leads, solderable per J-STD-002

ABSOLUTE MAXIMUM RATINGS										
PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS						
Peak repetitive reverse voltage	V_{RRM}		200	V						
Average rectified forward current	I _{F(AV)}	Total device, rated V _R , T _C = 150 °C	8							
Non-repetitive peak surge current	I _{FSM}		100	Α						
Peak repetitive forward current	I _{FM}	Rated V _R , square wave, 20 kHz, T _C = 150 °C	16							
Operating junction and storage temperatures	T _J , T _{Stg}		-65 to +175	°C						

ELECTRICAL SPECIFICATIONS (T _J = 25 °C unless otherwise specified)									
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS			
Breakdown voltage, blocking voltage	V_{BR} , V_{R}	I _R = 100 μA	200	-	-	.,			
F	V _F	I _F = 8 A	0.975	V					
Forward voltage		I _F = 8 A, T _J = 150 °C	-	-	0.895				
Reverse leakage current	I _R	$V_R = V_R$ rated	-	-	5				
neverse leakage current		$T_J = 150 ^{\circ}\text{C}, V_R = V_R \text{rated}$	-	-	250	μΑ			
Junction capacitance	C _T	$V_{R} = 200 \text{ V}$	-	25	-	pF			
Series inductance	L _S	Measured lead to lead 5 mm from package body	-	8.0	-	nΗ			



DYNAMIC RECOVERY CHARACTERISTICS (T _J = 25 °C unless otherwise specified)										
PARAMETER	SYMBOL	TEST CO	NDITIONS	MIN.	TYP.	MAX.	UNITS			
		$I_F = 1.0 A, dI_F/dt =$	$I_F = 1.0 \text{ A}, dI_F/dt = 50 \text{ A/}\mu\text{s}, V_R = 30 \text{ V}$			35				
Reverse recovery time	t _{rr}	$I_F = 0.5 \text{ A}, I_R = 1.0$	ı	ı	25					
		T _J = 25 °C		-	20	-	ns			
		T _J = 125 °C		-	34	-				
Dook roopyon, gurrent	I _{RRM}	T _J = 25 °C	I _F = 8 A dI _F /dt = 200 A/μs	-	1.7	-	Α			
Peak recovery current		T _J = 125 °C	$V_{\rm R} = 160 \text{ V}$	-	4.2	-	A			
Reverse recovery charge	Q _{rr}	T _J = 25 °C -	-	23	-	nC				
		T _J = 125 °C		-	75	-	TIC			

THERMAL - MECHANICAL SPECIFICATIONS										
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS				
Maximum junction and storage temperature range	T _J , T _{Stg}		-65	-	175	°C				
Thermal resistance, junction to case	R _{thJC}		-	-	3.0					
Thermal resistance, junction to ambient	R _{thJA}		-	-	50	°C/W				
Thermal resistance, case to heatsink	R _{thCS}	Mounting surface, flat, smooth, and greased	-	0.5	-					
Weight			-	2.0	-	g				
Mounting torque			6.0 (5.0)	-	12 (10)	kgf · cm (lbf · in)				
Marking device		Case style TO-220AC 2L	MUR820							

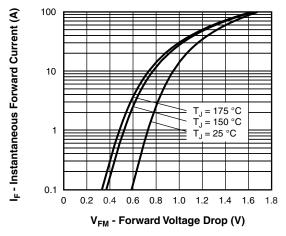


Fig. 1 - Maximum Forward Voltage Drop Characteristics

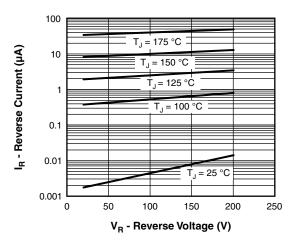


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage



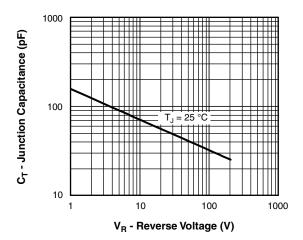


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

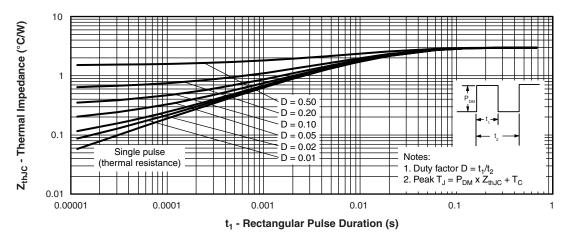


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics

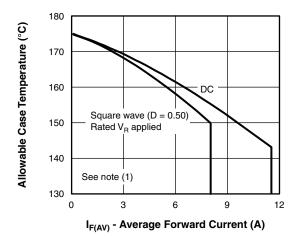


Fig. 5 - Maximum Allowable Case Temperature vs.
Average Forward Current

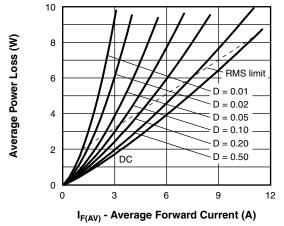


Fig. 6 - Forward Power Loss Characteristics

Note

⁽¹⁾ Formula used: T_C = T_J - (Pd + Pd_{REV}) x R_{thJC}; Pd = forward power loss = I_{F(AV)} x V_{FM} at (I_{F(AV)}/D) (see fig. 6); Pd_{REV} = inverse power loss = V_{R1} x I_R (1 - D); I_R at V_{R1} = rated V_R

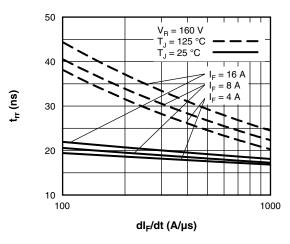


Fig. 7 - Typical Reverse Recovery Time vs. dl_F/dt

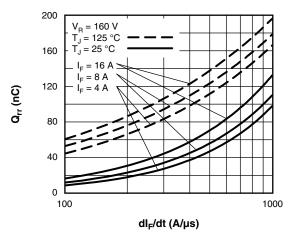
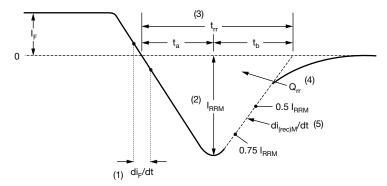


Fig. 8 - Typical Stored Charge vs. dl_F/dt



- (1) di_F/dt rate of change of current through zero crossing
- (2) I_{RRM} peak reverse recovery current
- (3) $\rm t_{rr}$ reverse recovery time measured from zero crossing point of negative going $\rm I_F$ to point where a line passing through 0.75 $\rm I_{RRM}$ and 0.50 $\rm I_{RRM}$ extrapolated to zero current.
- (4) $\rm Q_{rr}$ area under curve defined by $\rm t_{rr}$ and $\rm I_{RRM}$

$$Q_{rr} = \frac{t_{rr} x I_{RRM}}{2}$$

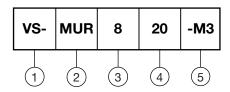
(5) di_{(rec)M}/dt - peak rate of change of current during t_b portion of t_{rr}

Fig. 9 - Reverse Recovery Waveform and Definitions



ORDERING INFORMATION TABLE

Device code



1 - Vishay Semiconductors product

Ultrafast MUR series

Current rating (8 = 8 A)

Voltage rating (20 = 200 V)

5 - Environmental digit:

-M3 = halogen-free, RoHS-compliant, and termination lead (Pb)-free

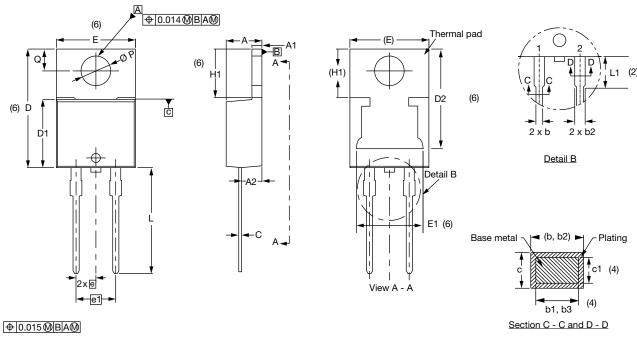
ORDERING INFORMATION (Example)									
PREFERRED P/N	BASE QUANTITY	PACKAGING DESCRIPTION							
VS-MUR820-M3	50	Antistatic plastic tube							

LINKS TO RELATED DOCUMENTS								
Dimensions	www.vishay.com/doc?96156							
Part marking information	www.vishay.com/doc?95391							
SPICE model	www.vishay.com/doc?96995							



TO-220AC 2L

DIMENSIONS in millimeters and inches



Lead tip

Conforms to JEDEC® outline TO-220AC

SYMBOL	MILLIMETERS		INC	HES	NOTES		NOTES		SYMBOL	MILLIN	IETERS	INC	HES	NOTES
STWIBUL	MIN.	MAX.	MIN.	MAX.	NOTES	NOTES	STMBOL	MIN.	MAX.	MIN.	MAX.	NOTES		
Α	4.25	4.65	0.167	0.183			D2	11.68	13.30	0.460	0.524	6, 7		
A1	1.14	1.40	0.045	0.055			E	10.11	10.51	0.398	0.414	3, 6		
A2	2.50	2.92	0.098	0.115			E1	6.86	8.89	0.270	0.350	6		
b	0.69	1.01	0.027	0.040			е	2.41	2.67	0.095	0.105			
b1	0.38	0.97	0.015	0.038	4		e1	4.88	5.28	0.192	0.208			
b2	1.20	1.73	0.047	0.068			H1	6.09	6.48	0.240	0.255	6		
b3	1.14	1.73	0.045	0.068	4		L	13.52	14.02	0.532	0.552			
С	0.36	0.61	0.014	0.024			L1	3.32	3.82	0.131	0.150	2		
с1	0.36	0.56	0.014	0.022	4		ØΡ	3.54	3.91	0.139	0.154			
D	14.85	15.35	0.585	0.604	3		Q	2.60	3.00	0.102	0.118			
D1	8.38	9.02	0.330	0.355										

Notes

- $^{(1)}$ Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Lead dimension and finish uncontrolled in L1
- (3) Dimension D, D1, and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- (4) Dimension b1, b3, and c1 apply to base metal only
- (5) Controlling dimensions: inches
- (6) Thermal pad contour optional within dimensions E, H1, D2, and E1
- (7) Outline conforms to JEDEC® TO-220, except D2



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Vishay

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